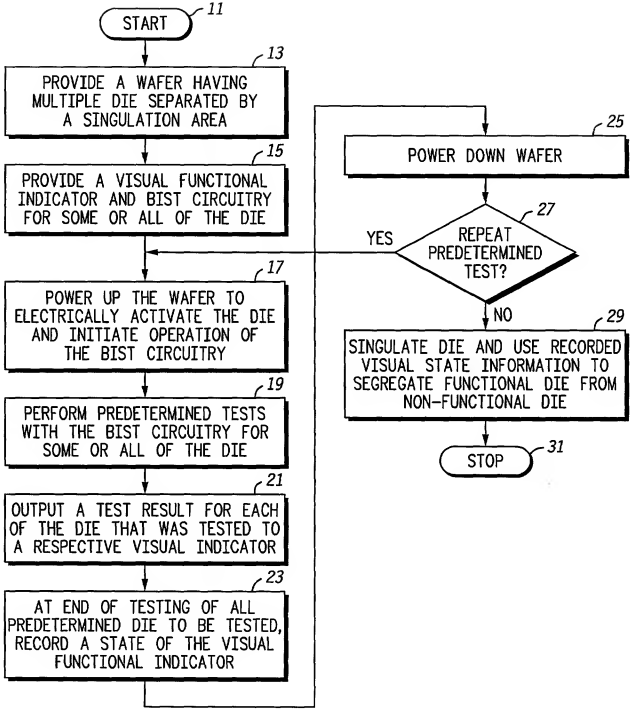

START
11
PROVIDE A WAFER HAVING MULTIPLE DIE SEPARATED BY A SINGULATION AREA
13
PROVIDE A VISUAL FUNCTIONAL INDICATOR AND BIST CIRCUITRY FOR SOME OR ALL OF THE DIE
15
POWER UP THE WAFER TO ELECTRICALLY ACTIVATE THE DIE AND INITIATE OPERATION OF THE BIST CIRCUITRY
17
PERFORM PREDETERMINED TESTS WITH THE BIST CIRCUITRY FOR SOME OR ALL OF THE DIE
19
OUTPUT A TEST RESULT FOR EACH OF THE DIE THAT WAS TESTED TO A RESPECTIVE VISUAL INDICATOR
21
AT END OF TESTING OF ALL PREDETERMINED DIE TO BE TESTED, RECORD A STATE OF THE VISUAL FUNCTIONAL INDICATOR
23
POWER DOWN WAFER
25
REPEAT PREDETERMINED TEST?
27
YES
NO
SINGULATE DIE AND USE RECORDED VISUAL STATE INFORMATION TO SEGREGATE FUNCTIONAL DIE FROM NON-FUNCTIONAL DIE
29
STOP
31

FIG.1

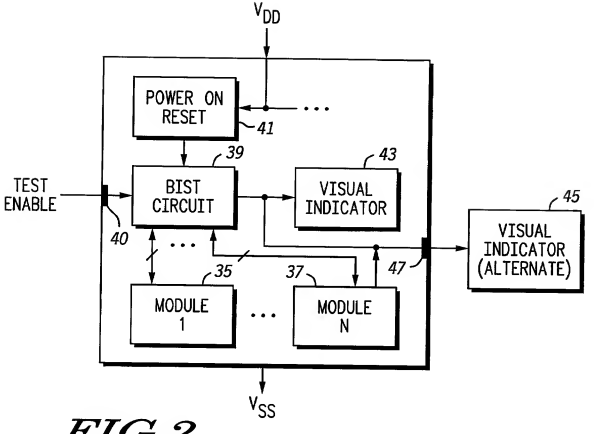


FIG.2

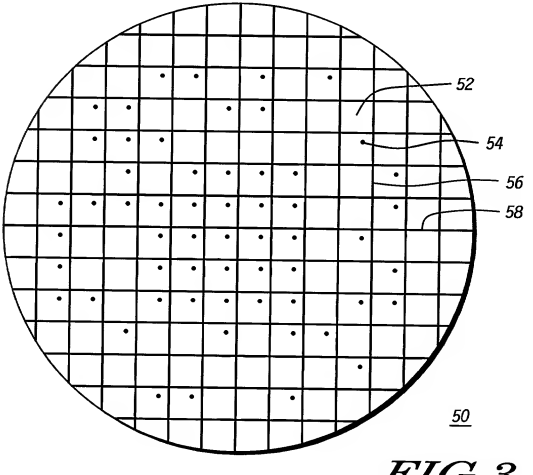
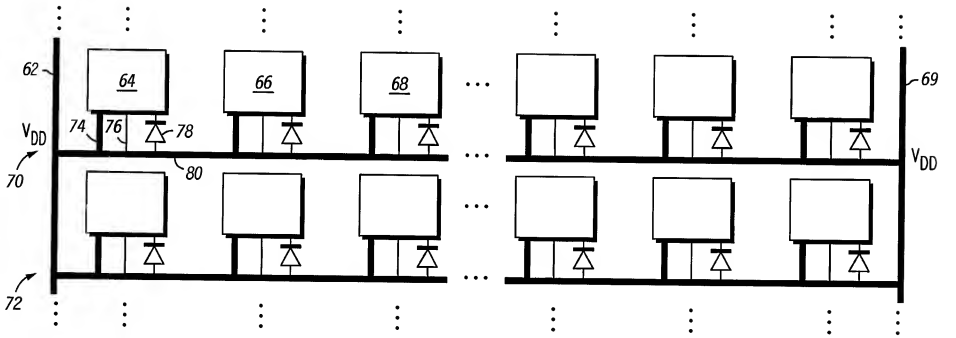


FIG.3



60

FIG.4